ASM3P2779A





Peak EMI Reducing Solution

Features

- Generates an EMI optimized clock signal at the output.
- Integrated loop filter components.
- Operates with a 3.3 / 2.5V Supply.
- Operating current less than 4mA.
- CMOS design.
- Input frequency range: 13MHz to 30MHz for 2.5V
 13MHz to 30MHz for 3.3V
- Generates a 1X low EMI spread spectrum clock of the input frequency.
- Frequency deviation: ±1% (Typ) @ 16MHz Input Frequency.
- Available in 6L-TSOP (6L-TSOT-23).

Product Description

The ASM3P2779A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. The ASM3P2779A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The ASM3P2779A allows significant system cost savings by reducing the number of circuit board layers, ferrite beads and shielding that are traditionally required to pass EMI regulations.

The ASM3P2779A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all digital method.

The ASM3P2779A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called 'spread spectrum clock generation.'

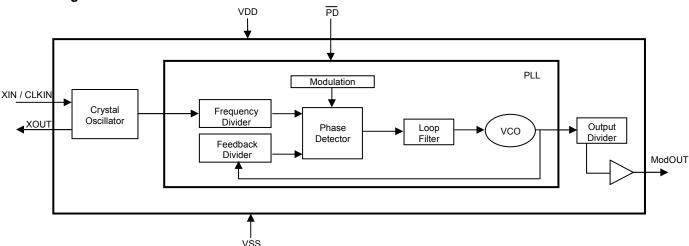
Applications

The ASM3P2779A is targeted towards all portable devices like MP3 players and digital still cameras.

Key Specifications

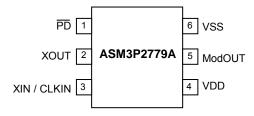
Description	Specification
Supply voltages	V _{DD} = 3.3V / 2.5V
Cycle-to-Cycle Jitter	±200pS (Typ)
Output Duty Cycle	45/55%
Modulation Rate Equation	F _{IN} /640
Frequency Deviation	±1% (Typ) @ 16MHz

Block Diagram



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Pin Configuration (6L-TSOP Package)



Pin Description

Pin#	Pin Name	Туре	Description				
1	1 PD I		Power-down control pin. Pull low to enable power-down mode. Connect to VDD if not used.				
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.				
3	XIN / CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.				
4	VDD	Р	Power supply for the entire chip.				
5	ModOUT	0	Spread spectrum clock output.				
6	VSS	Р	Ground connection.				

Specifications

Description		Specification
Fraguency Banga	For 2.5V Supply	13MHz < CLKIN < 30MHz
Frequency Range	For 3.3V Supply	13MHz < CLKIN < 30MHz
Modulation Equatio	n	F _{IN} /640
Frequency Deviation		±1% (Typ) @ 16MHz

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit				
VDD, V _{IN}	Voltage on any pin with respect to Ground	-0.5 to +4.6	V				
T _{STG}	Storage temperature	-65 to +125	$^{\circ}$				
T _A	Operating temperature	0 to +70	С				
Ts	Max. Soldering Temperature (10 sec)	260	$^{\circ}$				
TJ	Junction Temperature	150	$^{\circ}$				
T_DV	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV				
	Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.						

Operating Conditions

- por um 19 - c				
Parameter	Description	Min	Max	Unit
VDD	Supply Voltage	2.375	3.6	V
T_A	Operating Temperature (Ambient Temperature)	-40	+85	${\mathfrak C}$
C_L	Load Capacitance		15	pF
C_{IN}	Input Capacitance		7	pF

DC Electrical Characteristics for 2.5V Supply

Symbol	Parameter	Min	Тур	Max	Unit
V_{IL}	Input low voltage	VSS-0.3		0.8	V
V_{IH}	Input high voltage	2.0		VDD+0.3	V
I _{IL}	Input low current			-35	μA
I _{IH}	Input high current			35	μA
I _{XOL}	XOUT output low current (@ 0.5V, VDD = 2.5V)		3		mA
I _{XOH}	XOUT output high current (@ 1.8V, VDD = 2.5V)		3		mA
V _{OL}	Output low voltage (VDD = 2.5 V, I _{OL} = 8mA)			0.6	V
V _{OH}	Output high voltage (VDD = 2.5 V, I _{OH} = 8mA)	1.8			V
I _{DD}	Static supply current ¹			2.0	uA
Icc	Dynamic supply current (2.5V, 16MHz and no load)		3.0		mA
VDD	Operating Voltage	2.375	2.5	2.625	V
t _{ON}	Power-up time (first locked cycle after power-up) ²			5	mS
Z _{OUT}	Output impedance		50		Ω
	/ CLKIN pin and PD pin are pulled low. and XIN / CLKIN input are stable, PD pin is made high from low.				

AC Electrical Characteristics for 2.5V Supply

Symbol	Pa	Parameter		Тур	Max	Unit
CLKIN	Input frequency		13		30	MHz
ModOUT	Output frequency		13		30	MHz
£	Fraguency Deviation	Input Frequency = 13MHz		±1.15		0/
f _d	Frequency Deviation Input Frequence			±0.6		%
t _{LH} 1	Output rise time (measured f	Output rise time (measured from 0.7V to 1.7V)		1.4	1.8	nS
t _{HL} 1	Output fall time (measured fr	Output fall time (measured from 1.7V to 0.7V)		0.9	1.1	nS
t _{JC}	Jitter (cycle-to-cycle)	Jitter (cycle-to-cycle)		±200		pS
t _D	Output duty cycle		45	50	55	%
Note: 1. t _{LH} and t _{HL} are	measured into a capacitive load of 15pF.					

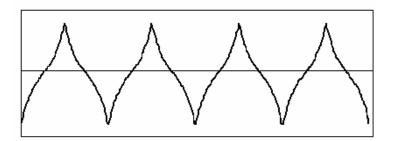
DC Electrical Characteristics for 3.3V Supply

Symbol	Parameter	Min	Тур	Max	Unit
VIL	Input low voltage	VSS-0.3		0.8	V
V _{IH}	Input high voltage	2.0		VDD+0.3	V
I _{IL}	Input low current			-35	μΑ
I _{IH}	Input high current			35	μA
I _{XOL}	XOUT output low current (@ 0.4V, VDD = 3.3V)		3		mA
I _{XOH}	XOUT output high current (@ 2.5V, VDD = 3.3V)		3		mA
V _{OL}	Output low voltage (VDD = 3.3 V, I _{OL} = 8mA)			0.4	V
V _{OH}	Output high voltage (VDD = 3.3 V, I _{OH} = 8mA)	2.5			V
I _{DD}	Static supply current ¹			2.0	uA
Icc	Dynamic supply current (3.3V, 16MHz and no load)		3.5		mA
VDD	Operating Voltage	2.7	3.3	3.6	V
t _{ON}	Power-up time (first locked cycle after power-up) ²			5	mS
Z _{OUT}	Output impedance		45		Ω
Notes: 1. XIN 2. V _{DD}	/ CLKIN pin and PD pin are pulled low. and XIN / CLKIN input are stable, PD pin is made high from low.				

AC Electrical Characteristics for 3.3V Supply

Symbol	Р	Parameter		Тур	Max	Unit				
CLKIN	Input frequency		13		30	MHz				
ModOUT	Output frequency		13	V	30	MHz				
£	Fraguency Deviation	Input Frequency = 13MHz		±1.15		%				
f _d	Frequency Deviation	Input Frequency = 30MHz		±0.6		70				
t _{LH} 1	Output rise time (measur	Output rise time (measured from 0.8 to 2.0V)		1.1	1.3	nS				
t _{HL} 1	Output fall time (measure	Output fall time (measured at 2.0V to 0.8V)		0.8	0.9	nS				
t _{JC}	Jitter (cycle-to-cycle)	Jitter (cycle-to-cycle)		±200		pS				
t _D	Output duty cycle		45	50	55	%				
1. t _{LH} and t _{HL} are me	easured into a capacitive load of 15pF.			•	ote: 1. t _{LH} and t _{HL} are measured into a capacitive load of 15pF.					

Modulation Profile

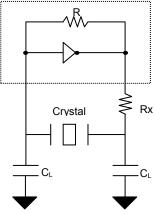


Typical Crystal Specifications

Fundamental AT cut parallel resonant crystal				
Nominal frequency	16MHz			
Frequency tolerance	± 50 ppm or better at 25℃			
Operating temperature range	-25℃ to +85℃			
Storage temperature	-40℃ to +85℃			
Load capacitance(C _P)	18pF			
Shunt capacitance	7pF maximum			
ESR	25 Ω			

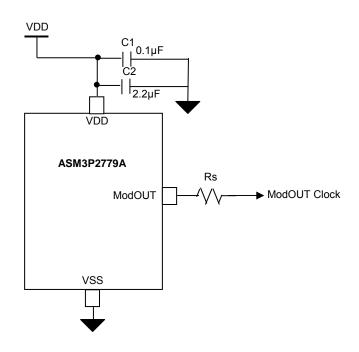
Note: Note: C_L is Load Capacitance and Rx is used to prevent oscillations at overtone frequency of the Fundamental frequency.

Typical Crystal Interface Circuit



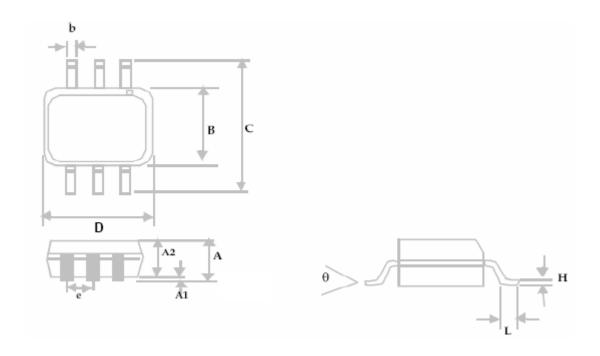
$$\begin{split} C_L &= 2^*(C_P - C_S),\\ \text{Where } C_P &= \text{Load capacitance of crystal}\\ C_S &= \text{Stray capacitance due to } C_{\text{IN}}, \text{PCB}, \text{Trace etc.} \end{split}$$

Typical Application Schematic



Package Information

6L-TSOP Package



		Dim	ensions	
Symbol	Inches		Millim	neters
	Min	Max	Min	Max
Α		0.04		1.00
A1	0.00	0.004	0.00	0.10
A2	0.033	0.036	0.84	0.90
b	0.012	0.02	0.30	0.50
Н	0.005	BSC	0.127	BSC
D	0.114	BSC	2.90	BSC
В	0.06	BSC	1.60	BSC
е	0.0374 BSC		0.950	BSC
С	0.11	BSC	2.80 BSC	
L	0.0118	0.02	0.30	0.50
θ	0°	4°	0°	4°

Ordering Information

Part Number	Marking	g Package Type	
ASM3P2779AF-06OR	A4L	6L-TSOP(6L-TSOT-23)., TAPE & REEL, Pb Free	0℃ to +70℃
ASM3I2779AF-06OR	A5L	6L-TSOP(6L-TSOT-23)., TAPE & REEL, Pb Free	-40℃ to +85℃

A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-free.

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